

# BpS12A03.50-06

## Features

- Surface Mount Devices
- Lead free device
- Size 4.5\*3.2 mm/0.18\*0.12 inch
- Surface Mount packaging for automated assembly

## Applications

- Almost anywhere there is a low voltage power supply, up to 60V and a load to be protected, including:
- Computer mother board, Modem, USB hub
  - PDAs & Charger, Analog & digital I line card
  - Digital cameras, Disk drivers, CD-ROMs,

## Performance Specification

Model	V <sub>max</sub> (Vdc)	I <sub>max</sub> (A)	I <sub>hold</sub> @25°C (A)	I <sub>trip</sub> @25°C (A)	P <sub>d</sub> Typ. (W)	Maximum Time To Trip		Resistance		Agency Approval	
						Current (A)	Time (Sec)	R <sub>1min</sub> (Ω)	R <sub>1max</sub> (Ω)	UL	TUV
BpS12A03.50-06		100	3.50	6.00	2.0	10.0	4.00	0.008	0.030		

**I<sub>hold</sub>** = Hold Current. Maximum current device will not trip in 25°C still air.

**I<sub>trip</sub>** = Trip Current. Minimum current at which the device will always trip in 25°C still air.

**V<sub>max</sub>** = Maximum operating voltage device can withstand without damage at rated current (I<sub>max</sub>).

**I<sub>max</sub>** = Maximum fault current device can withstand without damage at rated voltage (V<sub>max</sub>).

**P<sub>d</sub>** = Power dissipation when device is in the tripped state in 25°C still air environment at rated voltage.

**R<sub>1min/max</sub>** = Minimum/Maximum device resistance prior to tripping at 25°C.

**R<sub>1max</sub>** = Maximum device resistance is measured one hour post reflow.

**CAUTION** : Operation beyond the specified ratings may result in damage and possible arcing and flame.

## Environmental Specifications

Test	Conditions	Resistance change
Passive aging	+85°C, 1000 hrs.	±5% typical
Humidity aging	+85°C, 85% R.H., 168 hours	±5% typical
Thermal shock	+85°C to -40°C, 20 times	±33% typical
Resistance to solvent	MIL-STD-202, Method 215	No change
Vibration	MIL-STD-202, Method 201	No change
Ambient operating conditions : - 40 °C to +85 °C		
Maximum surface temperature of the device in the tripped state is 125 °C		

Agency Approvals :

UL pending

Regulation/Standard:



2002/95/EC



EN14582

## I<sub>hold</sub> Versus Temperature

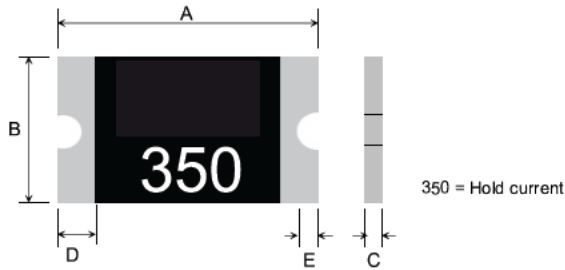
Model	Maximum ambient operating temperature (T <sub>max</sub> ) vs. hold current (I <sub>hold</sub> )								
	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
BpS12A03.50-06	4.84	4.39	4.04	3.50	2.98	2.66	2.35	1.88	1.55

# BpS12A03.50-06

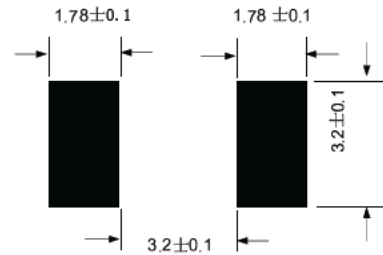
## Construction And Dimension (Unit:mm)

Model	A		B		C		D		E
	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.
BpS12A03.50-06	4.37	4.73	3.07	3.41	1.10	1.80	0.30		0.25

### Dimensions & Marking



### Recommended Pad Layout (mm)



### Termination Pad Characteristics

Terminal pad materials :

Tin-plated Nickel-Copper

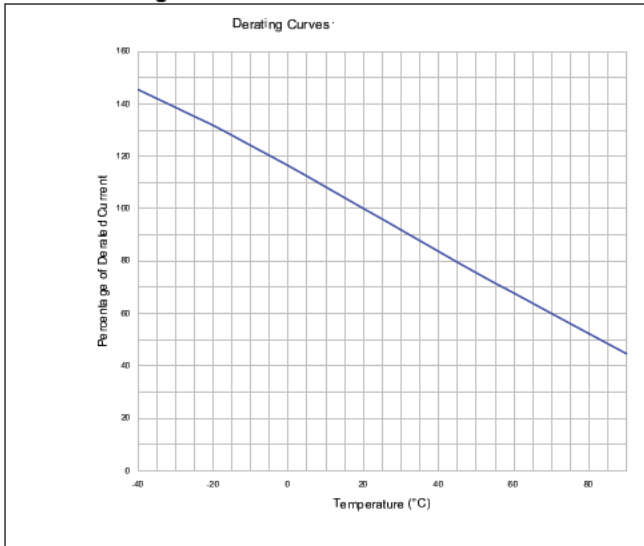
Terminal pad solderability :

Meets EIA specification RS186-9E and ANSI/J-STD-002 Category 3.

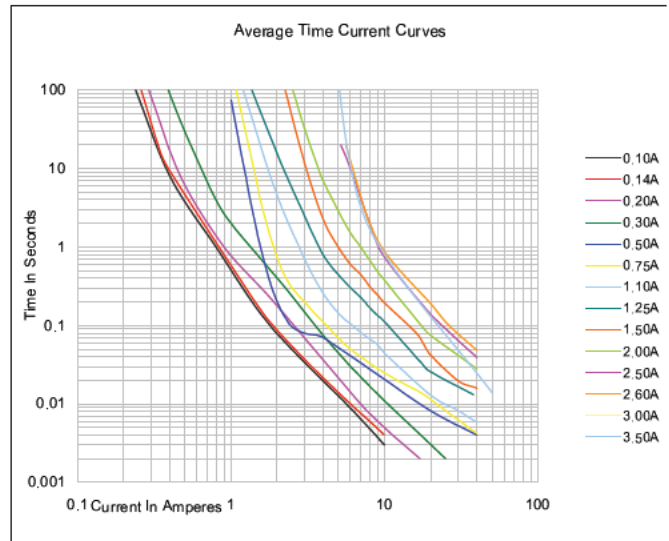
### Rework

Use standard industry practices, the removal device must be replaced with a fresh one.

### Thermal Derating Curve



### Typical Time-To-Trip At 25°C

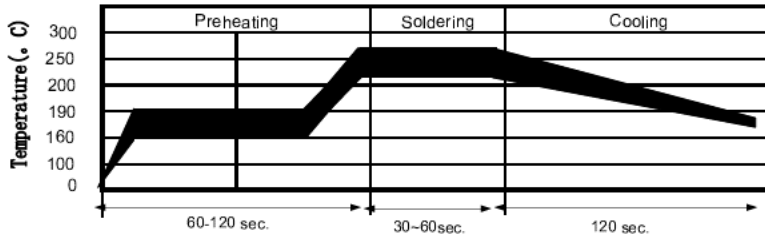


### WARNING:

- Use PPTC beyond the maximum ratings or improper use may result in device damage and possible electrical arcing and flame.
- PPTC are intended for protection against occasional over current or over temperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.
- Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, and mechanical procedures for electronic components.
- Use PPTC with a large inductance in circuit will generate a circuit voltage (L di/dt) above the rated voltage of the PPTC.
- Avoid impact PPTC device its thermal expansion like placed under pressure or installed in limited space.
- Contamination of the PPTC material with certain silicon based oils or some aggressive solvents can adversely impact the performance of the devices. PPTC SMD can be cleaned by standard methods.
- Requests that customers comply with our recommended solder pad layouts and recommended reflow profile. Improper board layouts or reflow profile could negatively impact solderability.

# BpS12A03.50-06

## Recommended Solder Reflow Conditions

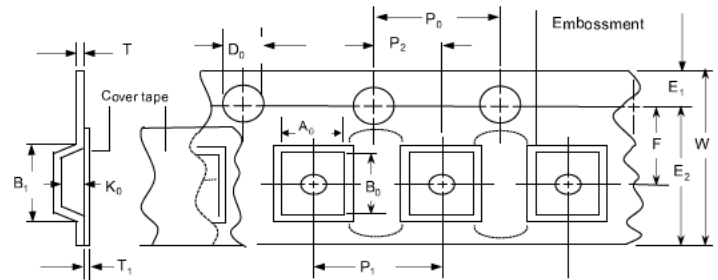


- Recommended reflow methods : IR, vapor phase oven, hot air oven.
  - Devices are not designed to be wave soldered to the bottom side of the board.
  - Recommended maximum paste thickness is 0.25 mm (0.010 inch).
  - Devices can be cleaned using standard method and solvents.
- Note : If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

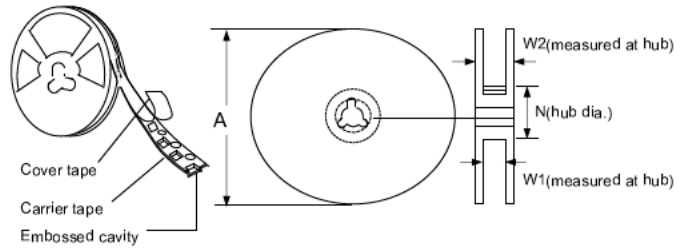
## Tape And Reel Specifications (mm)

Governing Specifications	EIA 481-1
W	12 ± 0.3
P0	4.0 ± 0.10
P1	8.0 ± 0.10
P2	2.0 ± 0.05
A0	3.5 ± 0.23
B0	5.1 ± 0.15
B1max.	5.9
D0	1.5 + 0.1, -0
F	5.5 ± 0.05
E1	1.75 ± 0.10
E2min.	10.25
Tmax.	0.6
T1max.	0.1
K0	0.9 ± 0.15
Leader min.	390
Trailer min.	160
<b>Reel Dimensions</b>	
A max.	178
N min.	60
W1	12.4 + 2.0, -0.0
W2max.	18.4

## EIA Tape Component Dimensions



## EIA Reel Dimensions



## Storage And Handling

- Storage conditions : 40°C max, 70% R.H.
- Devices may not meet specified performance if storage conditions are exceeded.